L Number	Hits	Search Text	DB	Time stamp
1	3	5198964.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/24 22:05
2	4650728	gold au	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/24 22:05
3	1	5198964.pn. and (gold au)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/24 22:11
4	1134943	lead leadframe (lead adj frame)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/24 22:12
5	5876	(lead leadframe (lead adj frame)) with (plated plating covered layer) with (gold au)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/24 22:13
6	997	((lead leadframe (lead adj frame)) with (plated plating covered layer) with (gold au)) same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/24 22:13
7	2119145	semiconductor die chip ic dice (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/24 22:15
8	496	package and (((lead leadframe (lead adj frame)) with (plated plating covered layer) with (gold au)) same solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/24 22:15
9	462	(semiconductor die chip ic dice (integrated adj circuit)) and (package and (((lead leadframe (lead adj frame)) with (plated plating covered layer) with (gold au)) same solder))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/24 22:16